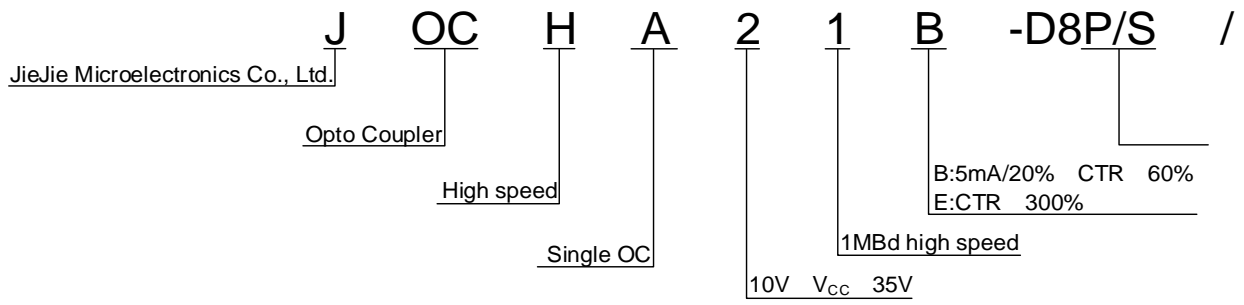




	Logic Low Output Voltage	V_{OL}	$I_F=16mA, I_O=2.4mA,$ $V_{CC}=4.5V$	-	-	0.4	V
	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	
	Floating Capacitance	C_{IO}	$V=0, f=1MHz$	-	0.8	-	pF
Switching Characteristics	Propagation Delay Time to Logic Low	TPHL	$I_F=0\ 16mA,$ $R_L=1.9k,$ $V_{CC}=5V$	-	-	0.8	μs
	Propagation Delay Time to Logic High	TPLH	$I_F=16\ 0mA,$ $R_L=1.9k,$ $V_{CC}=5V$	-	-	0.8	μs
	Common Mode Transient Immunity at Logic High	CMH	$I_F=0mA,$ $V_{CM}=400V_{pp},$ $R_L=4.1k$	15	20	-	kV/ μs
	Common Mode Transient Immunity at Logic Low	CM _L	$I_F=16mA,$ $V_{CM}=400V_{pp},$ $R_L=4.1k$	-15	-20	-	kV/ μs



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FIG.1: Forward Current vs. Forward Voltage

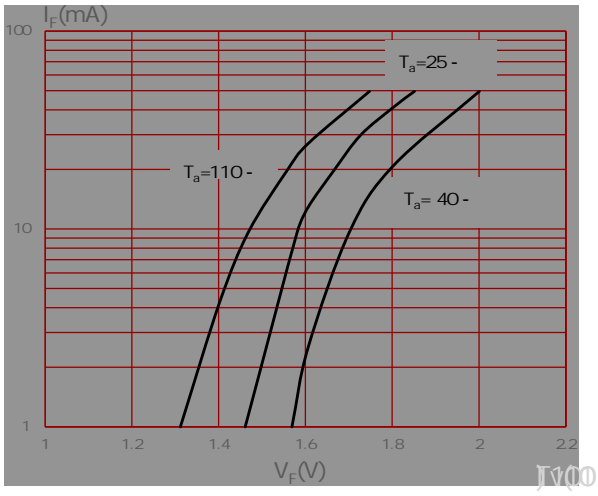


FIG.2: High Level Output Current vs. Ambient Temperature

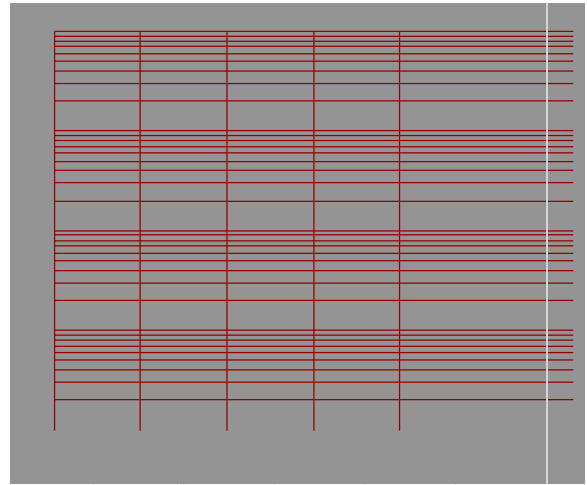


FIG.7: Low Level Output Voltage vs. Ambient Temperature

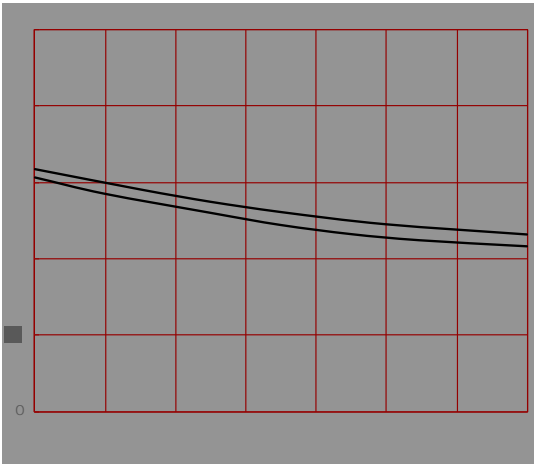
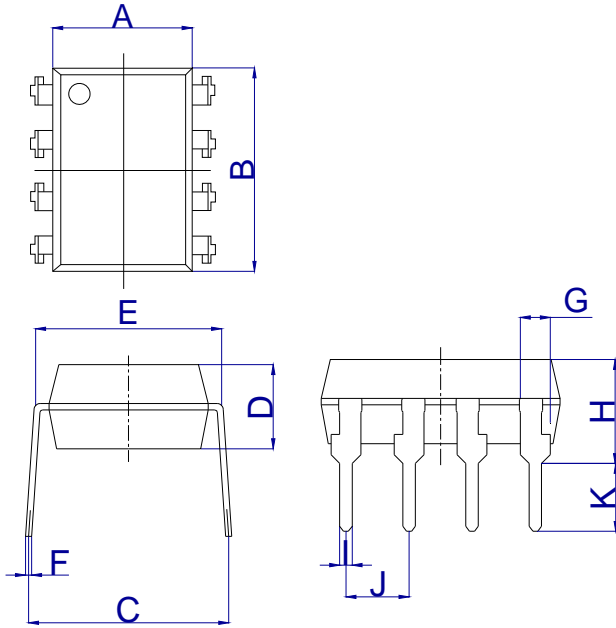


FIG.8: Propagation Delay vs. Load Resistance

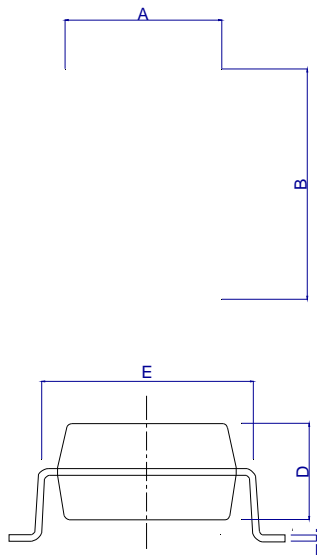
Package Description Unit: _____

Standard DIP Type:

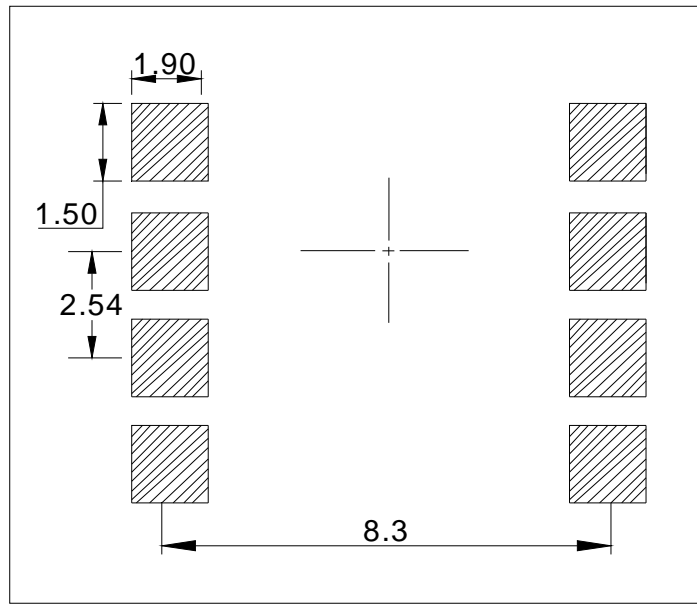


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

Option SMD Type:

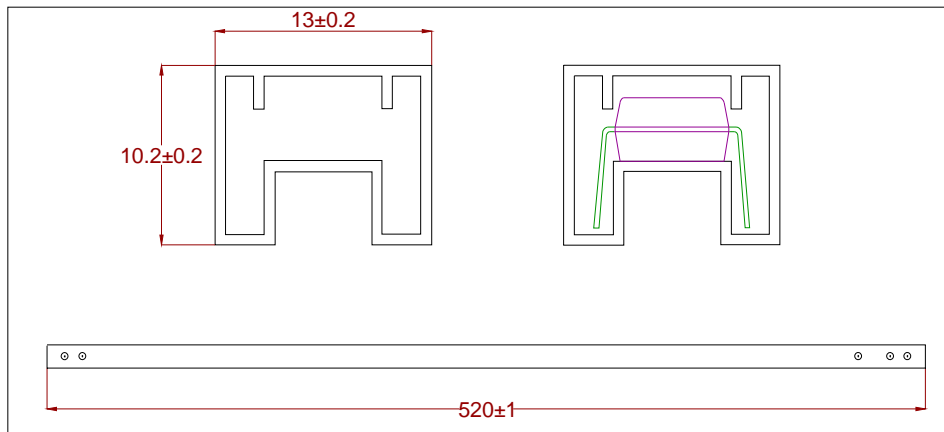


JEDEC SOLDED LEAD DIMENSIONS unless otherwise stated



STANDARD DIP DIMENSIONS unless otherwise stated

Standard DIP

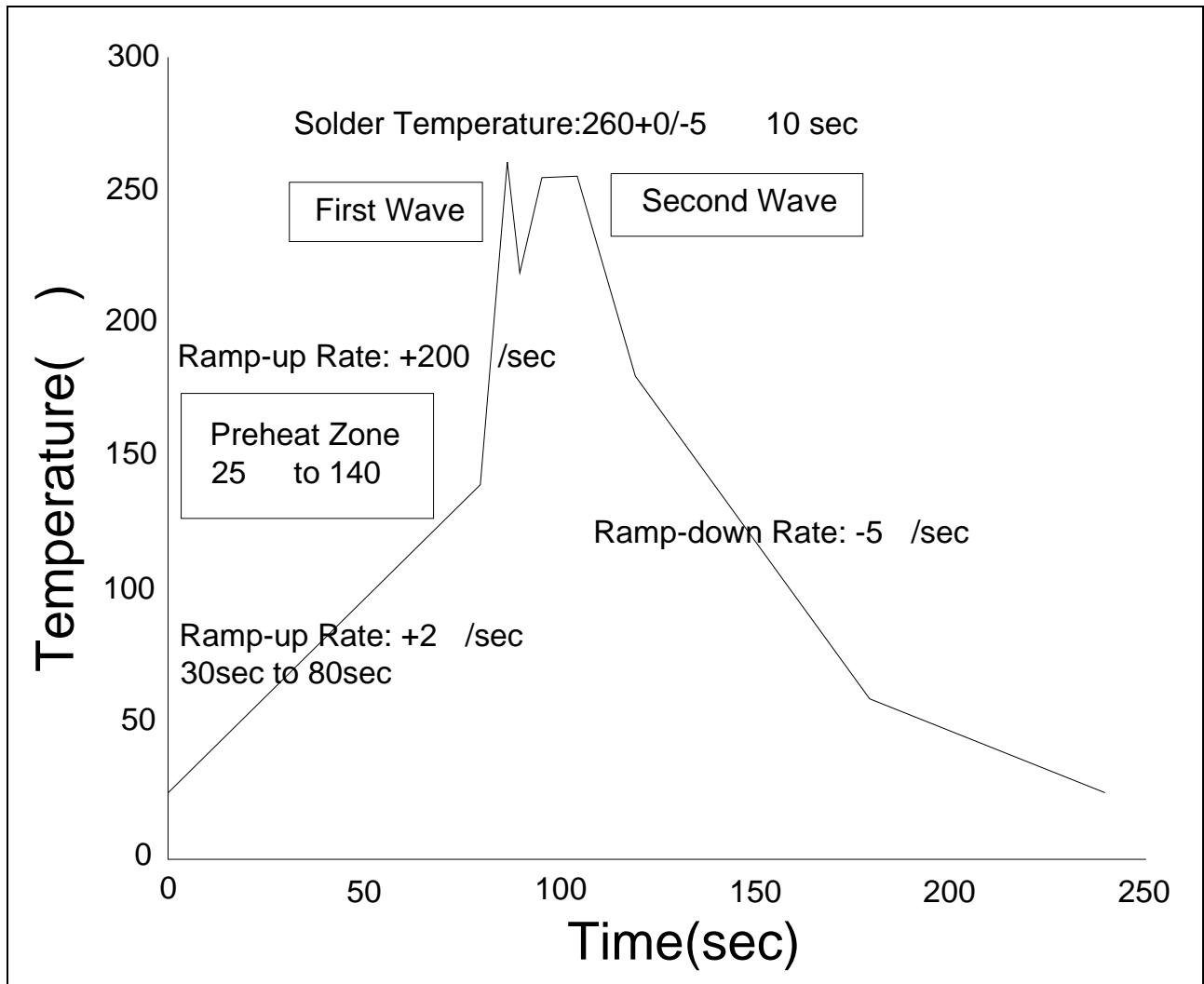




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Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50			0.059	
P0		4.00			0.157	
P1		12.00			0.472	
P2		2.00			0.079	
E		1.75			0.069	
F		7.50			0.295	
T		0.40			0.016	
W	15.90	16.00		0.626	0.630	

‡ A†E SOLDEKIV8



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Soldering Temperature	360 5
Soldering Time	3s max.

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